




IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-11
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

<b>Uncertainty Statement</b>			
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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	77CC*MV7UACC	A	CA2A	2017-01-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	13.2	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				 life.augmented
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Nickel/Gold (Ni/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LGA	2.5x3x0.86	14	No lead	
Comment	Package: A08N VFLGA2.5X3X.86 14L P.5 L.475X.25; MDF valid for LSM6DS3TR-C			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	77CC*MV7UACC		Lot 30001		Lot 30002 A	Lot 30002 B
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	6.674	mg	supplier	die	Silicon (Si)	7440-21-3		6.205	mg	929727	470076
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.015	mg	2248	1136
				supplier	metallisation	Copper (Cu)	7440-50-8		0.018	mg	2697	1364
				supplier	metallisation	Cobalt (Co)	7440-48-4		0.013	mg	1948	985
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.004	mg	599	303
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.006	mg	899	455
				supplier	metallisation	Tungsten (W)	7440-33-7		0.002	mg	300	152
				supplier	metallisation	Zirconium (Zr)	7440-67-7		0.002	mg	300	152
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.010	mg	1498	758
				supplier	passivation	Silicon Oxide	7631-86-9		0.080	mg	11987	6061
Substrate	Other Organic Materials	4.148	mg	JIG - R	die glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electro	0.319	mg	47797	24167
				supplier	core material	Fiber glass	65997-17-3		0.396	mg	95468	30000
				supplier	core material	Bisphenol F type epoxy resin	9003-36-5		0.221	mg	53279	16742
				supplier	core material	Bismaleimide (B)	105391-33-1		0.134	mg	32305	10152
				supplier	core material	Triazine (T)	25722-66-1		0.134	mg	32305	10152
				supplier	core material	metal hydroxide	21645-51-2		0.009	mg	2170	682
				supplier	core material	Zinc hydroxyde	20427-58-1		0.002	mg	482	152
				supplier	core material	Calcium sulfate	7778-18-9		0.005	mg	1205	379
				supplier	Solder mask	Acrylic resin	9003-01-4		0.058	mg	13983	4394
				supplier	Solder mask	Barium sulfate	7727-43-7		0.017	mg	4098	1288
				supplier	Solder mask	epoxy resin	85954-11-6		0.014	mg	3375	1061
				supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6		0.010	mg	2411	758
				supplier	Solder mask	aromatic hydrocarbon	Proprietary		0.007	mg	1688	530
				supplier	Solder mask	(2-methoxymethylethoxy)propanol	34590-94-8		0.003	mg	723	227
				supplier	Solder mask	Quartz	14808-60-7		0.001	mg	241	76
	Copper & its alloys			supplier	metallisation	Copper (Cu)	7440-50-8		3.080	mg	742527	233333
	Precious metals			supplier	metallisation	Nickel (Ni)	7440-02-0		0.050	mg	12054	3788
	Precious metals			supplier	metallisation	Gold (Au)	7440-57-5		0.007	mg	1688	530
Die attach	Other Organic Materials	0.295	mg	supplier	tape	epoxy resin	25068-38-6		0.186	mg	630508	14091
				supplier	tape	Polypropylene	9003-07-0		0.006	mg	20339	455
				supplier	tape	epoxy resin	29690-82-2		0.029	mg	98305	2197
				supplier	tape	propenoate polymer	538311-13-6		0.059	mg	200000	4470
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.015	mg	50847	1136
Bonding wire	Precious metals	0.192	mg	supplier	wire	Gold (Au)	7440-57-5		0.190	mg	989583	14394
				supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	10417	152
encapsulation	Other Organic Materials	1.891	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1.711	mg	904812	129621
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.047	mg	24855	3561
				supplier	mold compound	Epoxy Resin	Proprietary		0.076	mg	40190	5758
				supplier	mold compound	Phenol Resin	Proprietary		0.047	mg	24855	3561
				supplier	mold compound	Carbon black	1333-86-4		0.010	mg	5288	758